

TECHNICAL DATA SHEET

SnPb40 SOLDER STICKS

PRODUCT DESCRIPTION

PAI SnPb40 Sticks are being formulated with High Virgin Raw Metals Processed in state-of-the-art Vaccualloy Technology that brings world class Quality along. Here, Oxygen interaction with Alloy is Nil and thus, Dross formulation is reduced at PCB Assembly Process. Also an increase flow rate & reduced impurities found. PAI SnPb40 Alloy is compatible for a typical range of Flux Application Formulas used in Electronics Industry Today.

STORAGE AND HANDLING

- Do not use Fire near storage area.
- > Store in Dry, Cool and Non-Corrosive environment.
- Wear Personal Protective Equipments while Handling.
- Wear Personal Protective Equipments while Processing.

ALLOY COMPOSITION

SI No	Metal	PAI Sn60Pb40 Solder Sticks	ISO9453 Specification	J-STD-006 Specification
1	Sn	60.145% Max	59.5% -61.50%	59.5% -61.50%
2	Pb	Rem	Rem	Rem
3	Sb	0.00131% Max	0.05% Max	0.5% Max
4	Cu	0.00134% Max	0.05% Max	0.08% Max
5	Au	0.00078% Max	0.05% Max	NA
6	Ag	0.00073% Max	NA	0.10 Max%
7	Al	0.00026% Max	0.001% Max	0.005% Max
8	As	0.00108% Max	0.03% Max	0.03% Max
9	Bi	0.00196% Max	0.05% Max	0.25% Max
10	Cd	0.00136% Max	0.002% Max	0.001%Max
11	In	0.00324% Max	NA	NA
12	Fe	0.00931% Max	0.02% Max	0.02% Max
13	Ni	0.00228% Max	NA	0.01% Max
14	Zn	0.00068% Max	0.001% Max	0.003% Max
15	S	0.00045% Max	NA	NA



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PERSANG ALLOY INDUSTRIES PVT. LTD.



PHYSICAL CHARACTERISTICS OF APPLICATION

Alloy	Sn60/Pb40	
Shape	Rectangular Form	
Density	8.4gm/cm³ at 20 ⁰ C	
Melting Point	183°C	
Package Form	25Kgs	
Application	Wave Soldering / HASL Process	
Standards Considered	JIS-Z-3282	
Shelf Life	10 Years	

TECHNICAL SPECIFICATIONS

Technical Factors Recommended	Specifications
Solder Pot Temperature	250°C to 260°C
Dwell Time	2 Sec to 4 Sec
Immersion	0.5% to 0.70% of PWBs Thickness that being Processed
Dross Recovery	Once in Every 8 Hours
Impurities Level Check	In-House Specifications
Other Factors	Refer Liquid Flux Manufacturer Specifications for desired Yields

<u>Note</u>: The recommendations stated above have been contributed for desired Solder Joints and shall modify if required based on the end user Specifications.

For more details, please visit Our Website at www.persangalloy.com or write to us.





